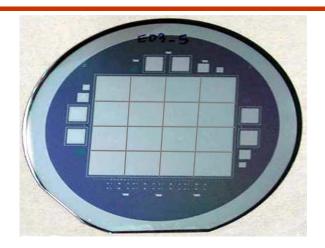
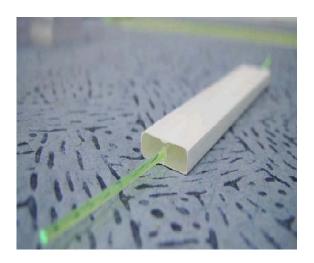
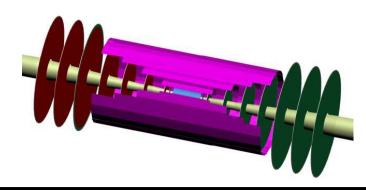
# **ILC Detector Activities in Korea**



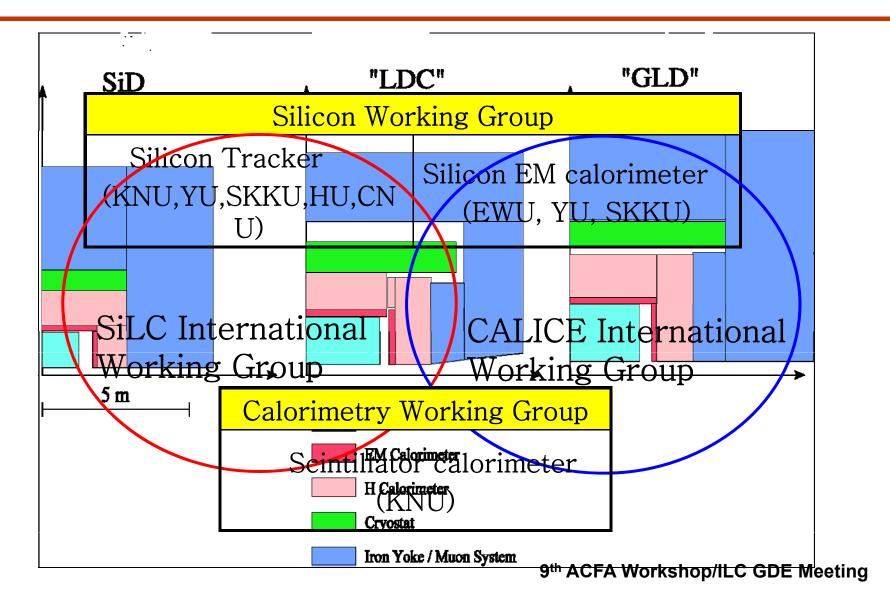




- Introduction
- Calorimeter
  - Silicon/Tungsten Ecal.
  - Scintillator Cal.
- Silicon Tracker
  - Simulation
  - Mechanical/Supporting Structures
  - Sensor Development
  - Beam Test
- Summary

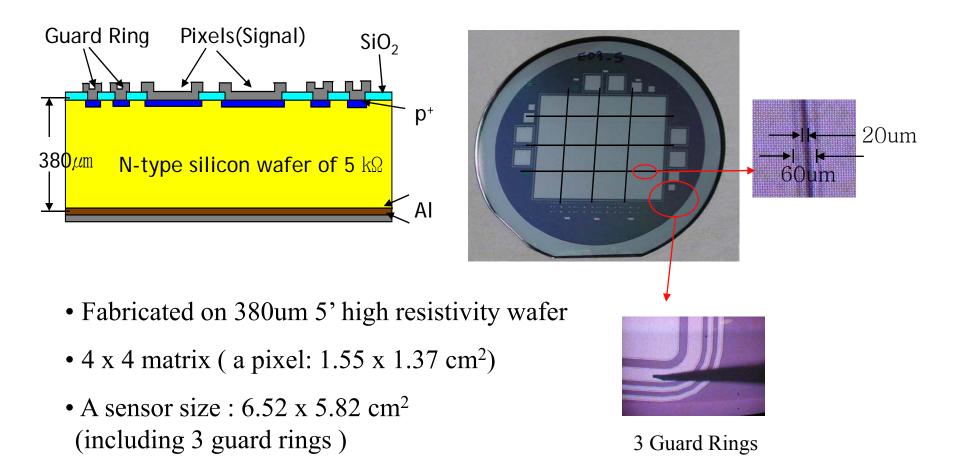
H. Park (Kyungpook Nat'l Univ.)

## **ILC Detector R&D Group in Korea**

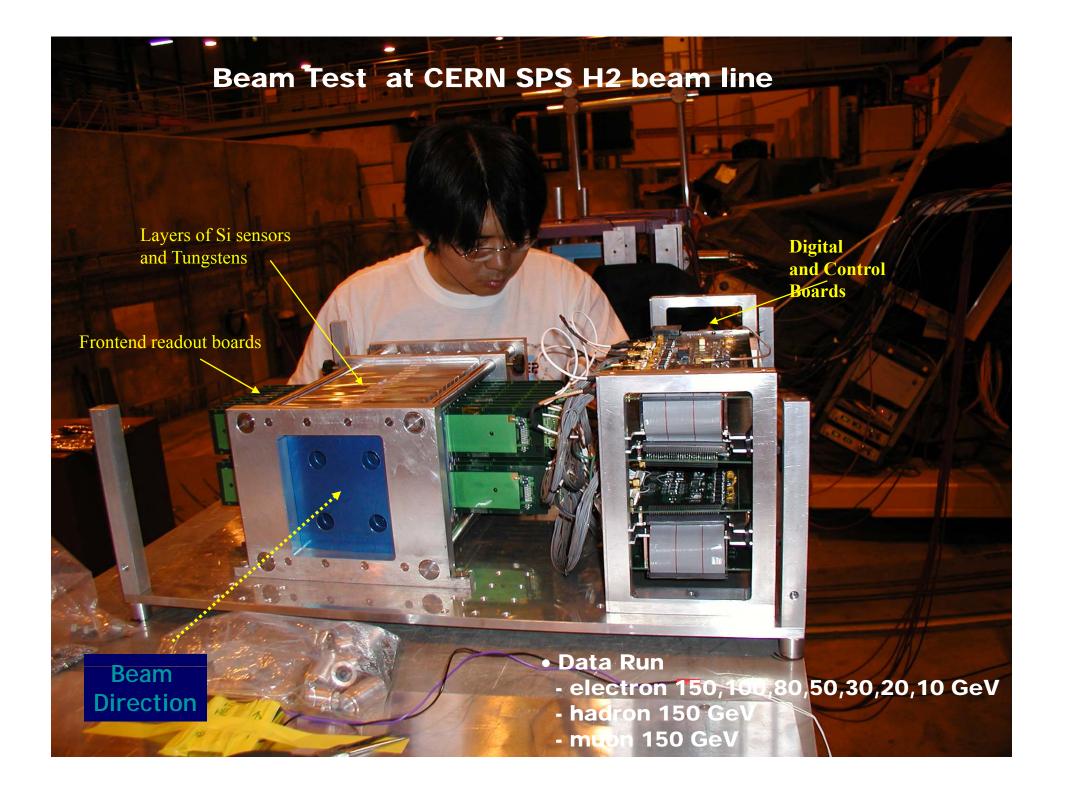


### **Si/W Calorimeter as Main EMCal**

## **Silicon Sensor for EM Calorimeter**

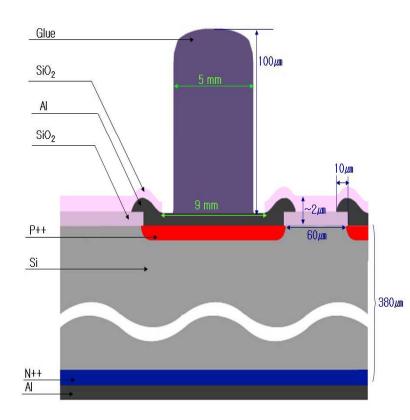


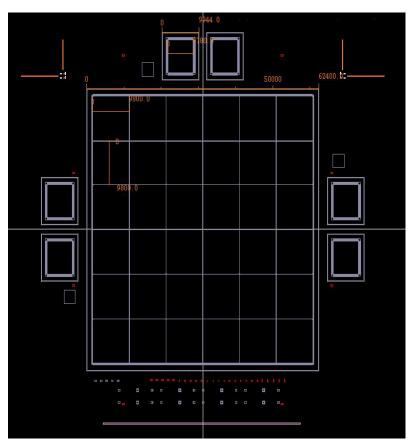
• DC coupled



#### **Sensor Revision**

beam test at CERN in last september (CALICE)
another revision/fabrication is in progress



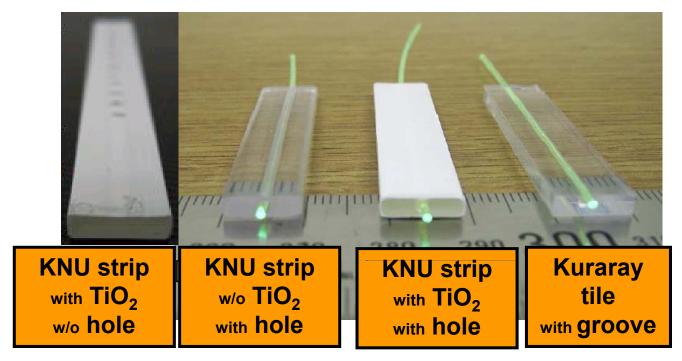


### **Scintillator Calorimeter**

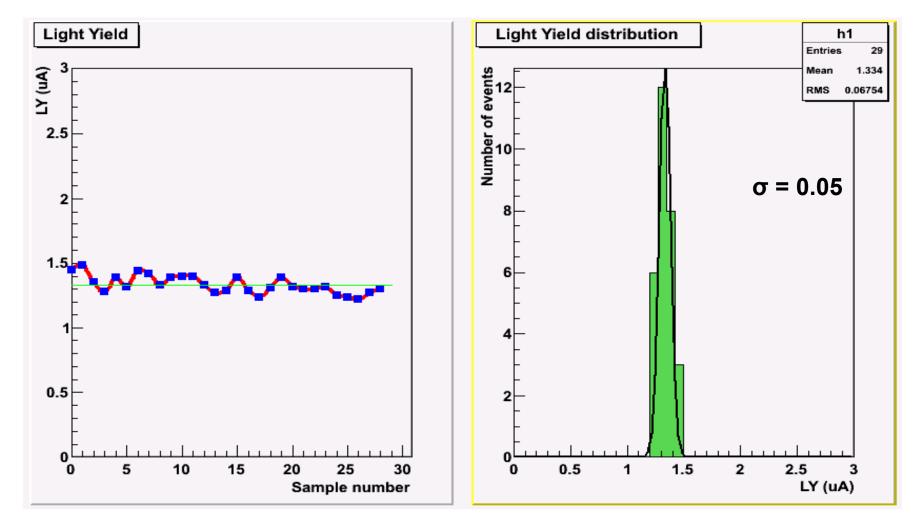
S. Chang (KNU) talk in Calorimeter session on Feb 6.

### **Extruded Plastic Scintillator**

- Extrusion is easy to make numerous type of scintillator
- Lower cost than casting method
  - primary dopants: PPO
  - secondary dopants: POPOP

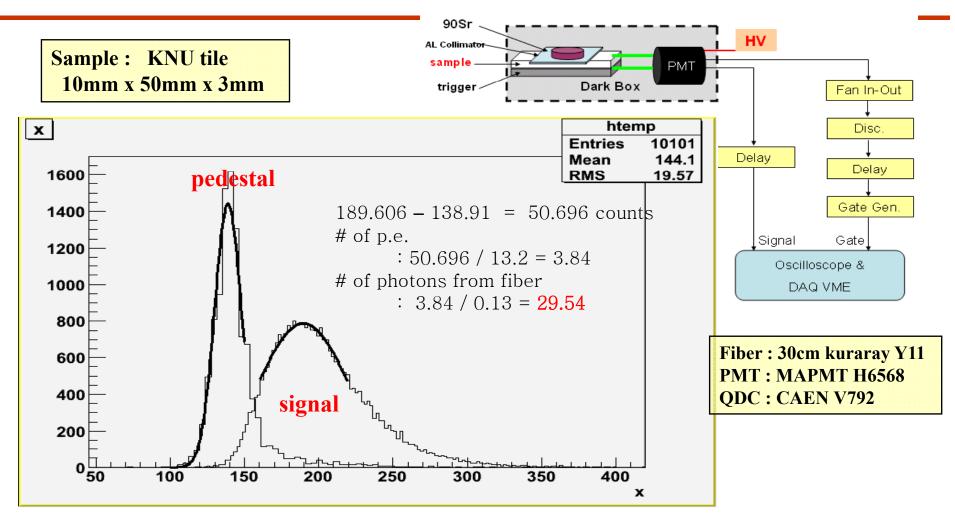


## **Light Yield Uniformity for all strips**



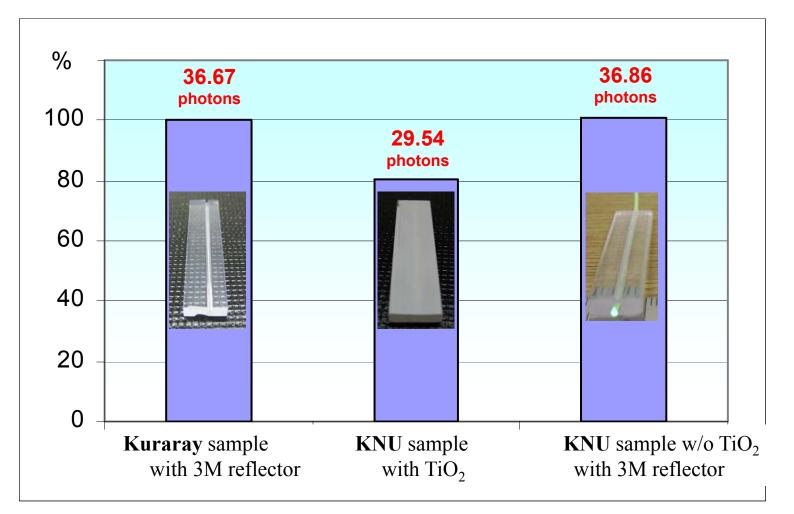
<sup>9&</sup>lt;sup>th</sup> ACFA Workshop/ILC GDE Meeting

### **Measurement of absolute Light Yield**



# of photon from fiber =  $\frac{\text{Pulse height (ADC counts)}}{13.2 (ADC count / 1pe) * Q.E.} = ~ 30 \text{ photons}$ Heeting

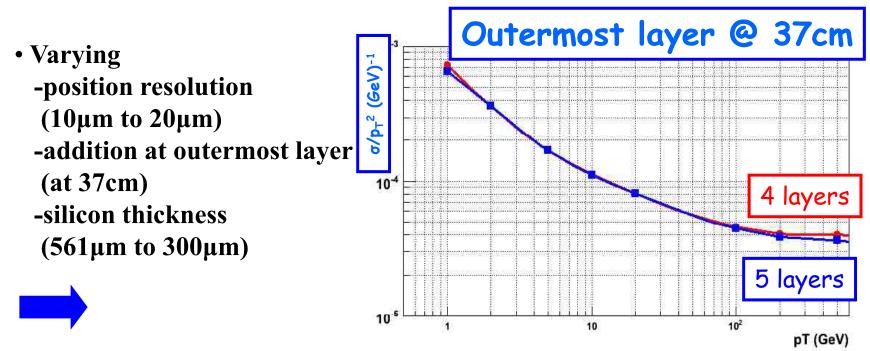
#### **Light Yield Comparison**



#### **Silicon Tracker**

H.J. Kim (KNU) talk in Tracking session on Feb 6.

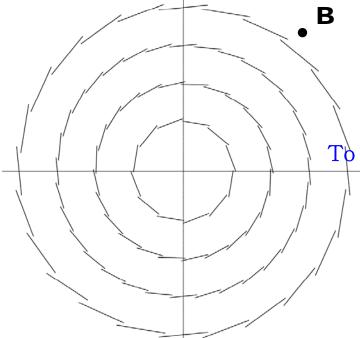
## **Simulation Studies**



and checked the momentum resolution, but did not find significant changes

So far, the current configuration seems to be good

### **Barrel Inner Tracker Configuration**



BIT	Half Z	Real Z ( o 1.6 mm)	R	sensor type	
layer 1	185	195.2	90	50 X 50	5.76°
layer 2	330	340.4	160	50 X 50	5.76°
layer 3	475	485.6	230	50 X 50	5.76°
layer 4	620	620.4	300	90 X 90	5.76°

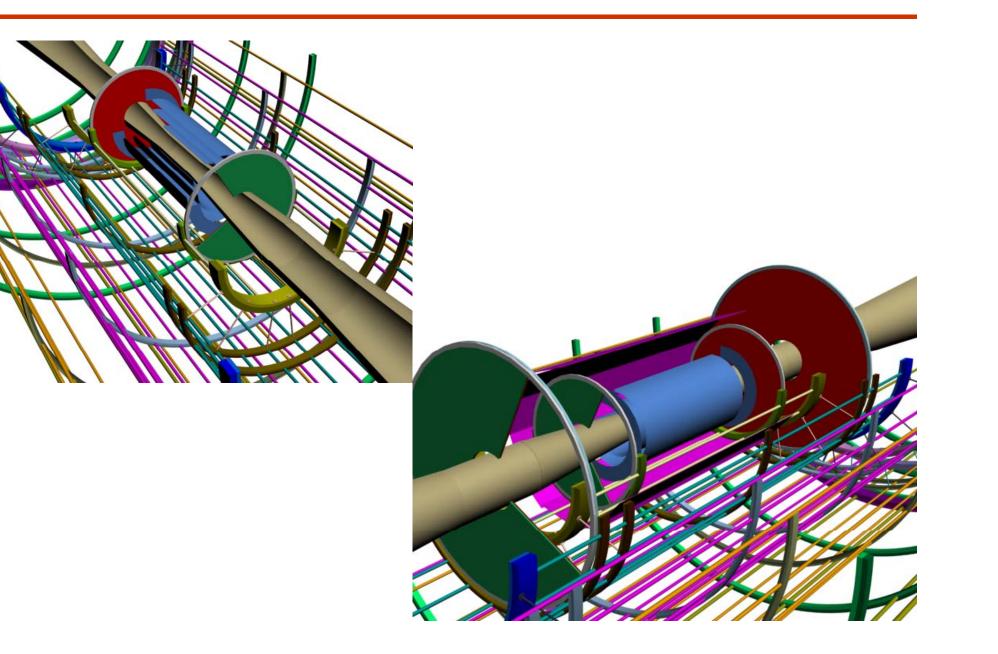
To make dead region free, module has 1.6 mm overlap

BIT	sensor area	# sensor of a module ( o 1.6)	# module	# sensor	total area
layer 1	50 X 50	4	24	96	240000 MM <sup>2</sup>
layer 2	50 X 50	7	48	336	840000 MM <sup>2</sup>
layer 3	50 X 50	10	64	640	1600000 MM2
layer 4	90 X 90	7	24	168	1360800 MM <sup>2</sup>

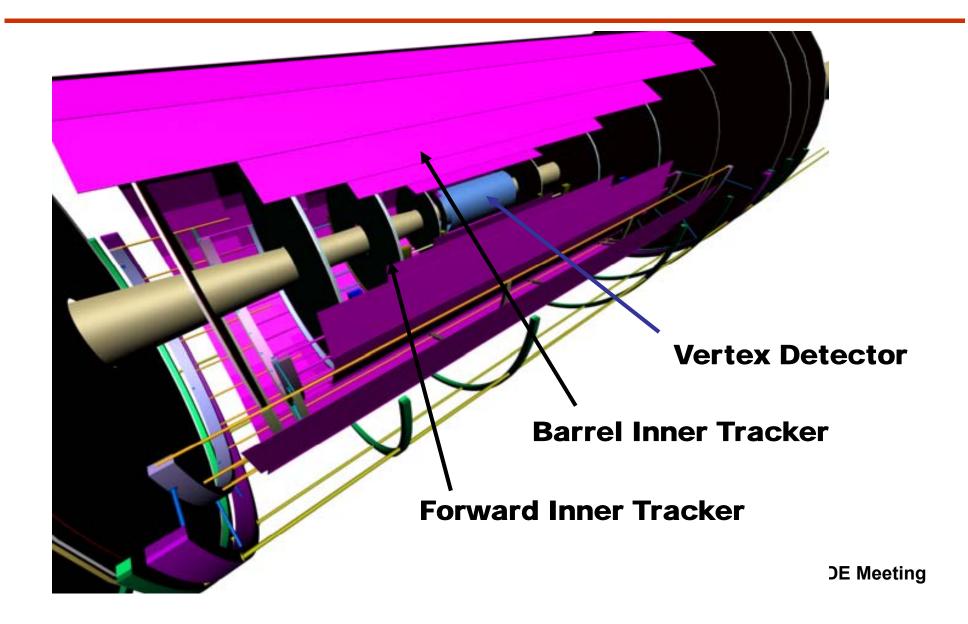
The Lorentz angle in a 3 T magnetic field  $\theta_L$  for electron : 24.97

 $\theta_{\rm L}$  for hole : 5.76

## **IT Mechanical Structure**

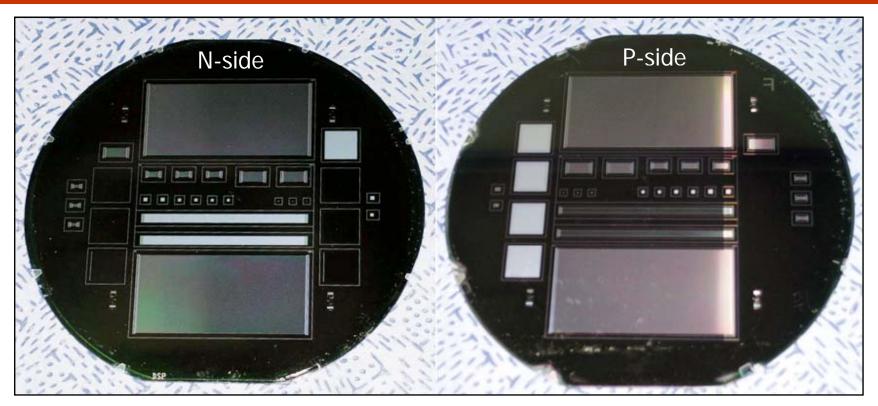


## **IT Mechanical Structure**



### **Silicon Sensor Fabrication**

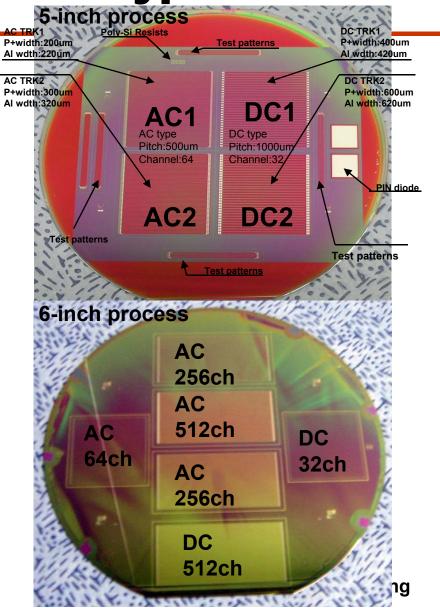
## **DC-DSSD** Prototype



	TOPSIL	strip width	9µm	
wafer	(5inch, high resistivity, (100), FZ, DSP)	strip pitch	50(100)µm	
thickness	380 μm	readout pitch	50µm	
size	51 x 26 mm <sup>2</sup>	readout channel	/ILC GDE Meeting 512(512)	

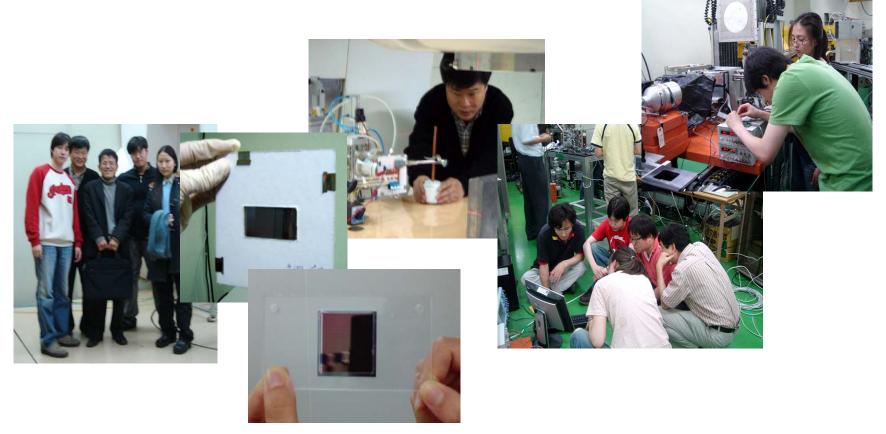
## **AC/DC SSD Prototype**

AC-coupled Single-sided Silicon Strip Detector						
	5-inch		6-inch			
thckness(µm)	3	80	400			
Area (µm <sup>2</sup> )		00  imes 000	55610 x 29460			
Effective area ( $\mu m^2$ )		70  imes 970	51264 x 25178			
SiO <sub>2</sub> layer thickness (nm)	1000		250			
Polysilicon length (µm)	10		8			
Polysilicon width (µm)	13500 48		48	0		
sheet resistance(k $\Omega$ )	~	25	~40	00		
	Type 1	Type2	Type 1	Typ e2		
Number of strips	64	64	256	512		
Strip pitch (µm)	500	500	100	50		
Strip width (µm)	200	300	8	8		
readout width (µm)	220	320	12	12		

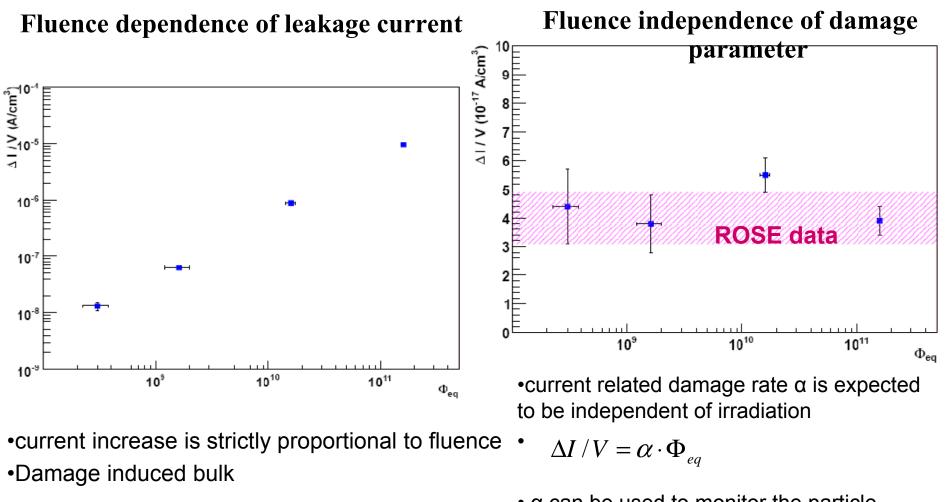


### **Radiation Damage/ Beam Test**

Cyclotron in Korea Institute of Radiological and Medical Science : 35~45 MeV proton cyclotron

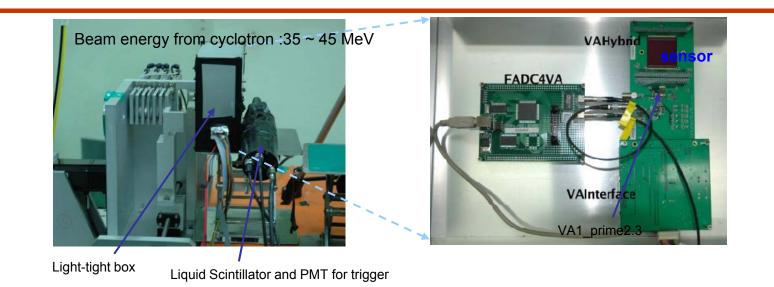


## **Radiation Damage Test**

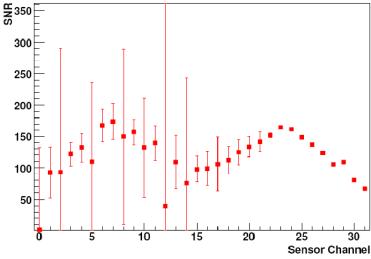


• α can be used to monitor the particle 9<sup>th</sup> ACFA Workshop/ILC GDE Meeting

### **Beam Test at KIRAMS**



SNR measurement results of each channel

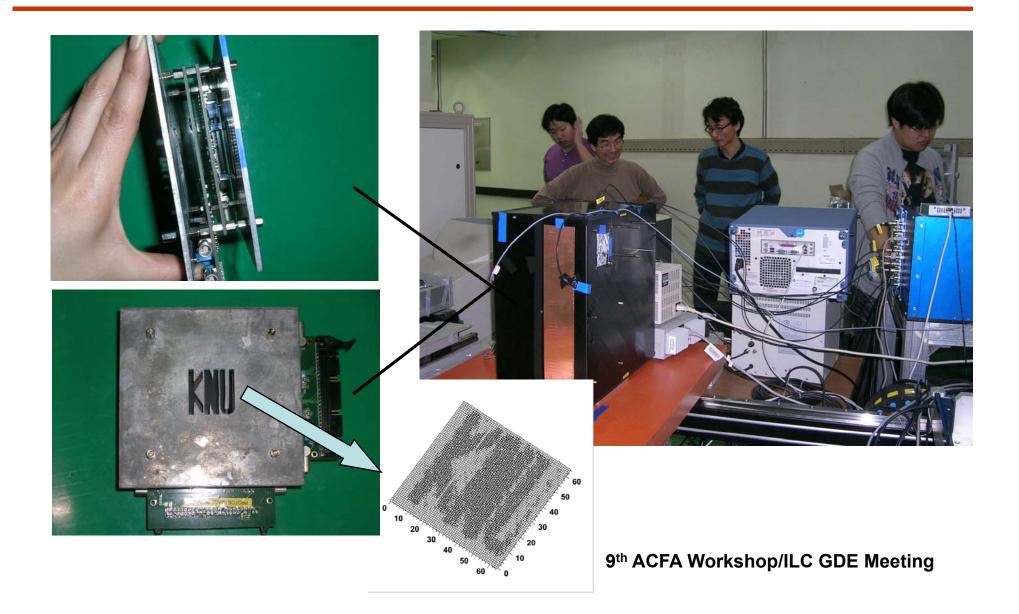


•The estimated S of N ratio of channel 0 to channel 22 have large errors because of few properly triggered events.

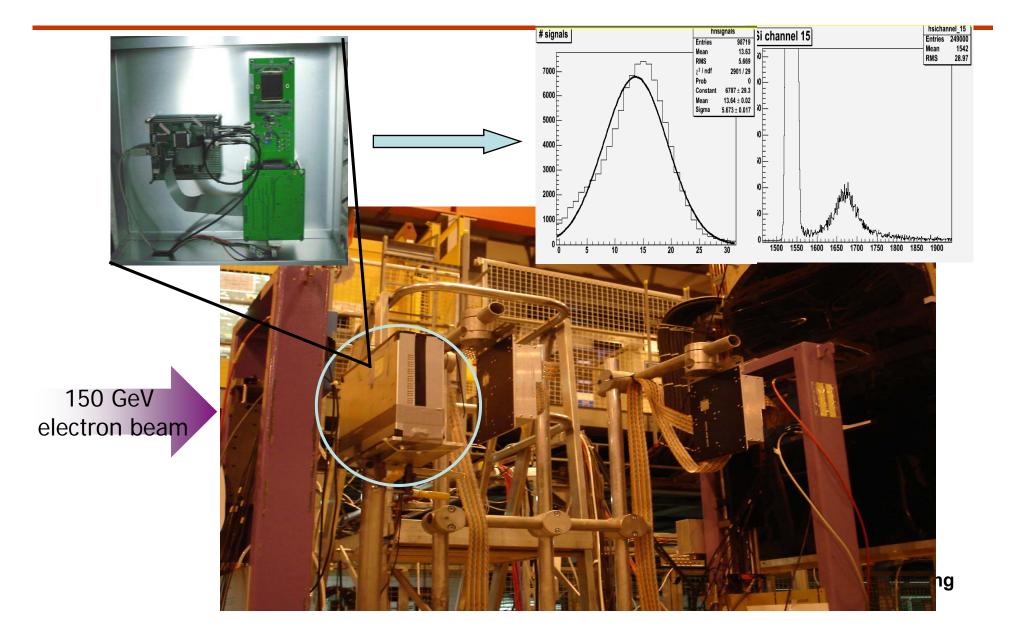
•Channels from 23 to 31 show good S of N ratio of between **67 and 164**.

•If we correct this values for a **1MIP**, it corresponds about **7 to 17** of SNR.

#### **Beam Test at KIRAMS**



### **Beam Test at CERN**



### Summary

 $\sqrt{100}$  sensor fabrication and beam test for EM calorimeter  $\sqrt{100}$  detector configuration of FCAL/BCAL in progress

 $\checkmark$  extrusion scintillator properties were tested

- good light yielding and uniformity
- beam test is scheduled in early spring

 $\checkmark$  Mega strip concept is developed and will be produced soon

 $\checkmark$  sensor fabrication and beam test for DC-DSSD and AC/DC-SSD  $\checkmark$  detector configuration of SIT (BIT and FIT)

 $\sqrt{1}$  funding project will be reviewed/renewed in spring.